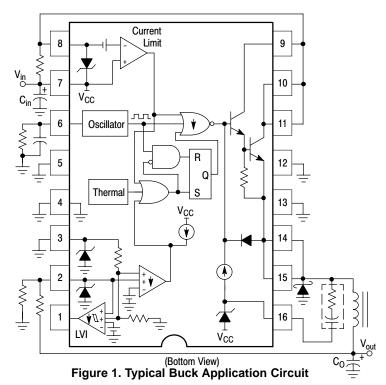
3.4 A, Step-Up/Down/ Inverting 50-300 kHz Switching Regulator

The NCP3163 Series is a performance enhancement to the popular MC33163 and MC34163 monolithic DC–DC converters. These devices consist of an internal temperature compensated reference, comparator, controlled duty cycle oscillator with an active current limit circuit, driver and high current output switch. This controller was specifically designed to be incorporated in step–down, step–up, or voltage–inverting applications with a minimum number of external components. The NCP3163 comes in an exposed pad package which can greatly increase the power dissipation of the built in power switch.

Features

- Output Switch Current in Excess of 3.0 A
- 3.4 A Peak Switch Current
- Frequency is Adjustable from 50 kHz to 300 kHz
- Operation from 2.5 V to 40 V Input
- Externally Adjustable Operating Frequency
- Precision 2% Reference for Accurate Output Voltage Control
- Driver with Bootstrap Capability for Increased Efficiency
- Cycle-by-Cycle Current Limiting
- Internal Thermal Shutdown Protection
- Low Voltage Indicator Output for Direct Microprocessor Interface
- Exposed Pad Power Package
- Low Standby Current
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes
- These are Pb–Free Devices



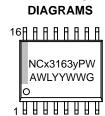


ON Semiconductor®

http://onsemi.com



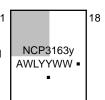
SOIC-16W EXPOSED PAD PW SUFFIX CASE 751AG



MARKING



18-LEAD DFN MN SUFFIX CASE 505



NCx3163x = Specific Device Code

x = P or V

y = blank or B

A = Assembly Location

WL = Wafer Lot
YY = Year
WW = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 18 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

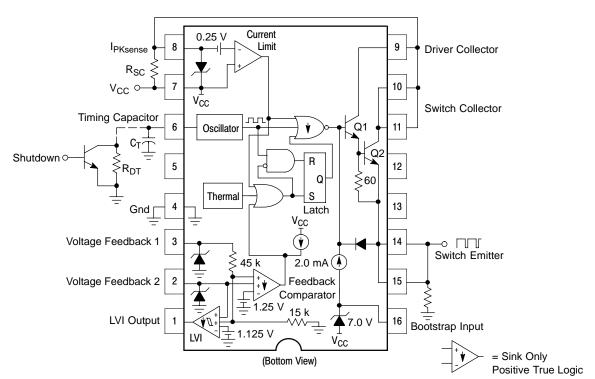


Figure 2. Representative Block Diagram

PIN FUNCTION DESCRIPTION

SOIC16	DFN18	PIN NAME	DESCRIPTION
1	15	LVI Output	This pin will sink current when FB1 and FB2 are less than the LVI threshold (Vth).
2	16	Voltage Feedback 2	Connecting this pin to a resistor divider off of the output will regulate the application according to the V _{out} design equation in Figure 22.
3	17	Voltage Feedback 1	Connecting this pin directly to the output will regulate the device to 5.05 V.
4	18	GND	Ground pin for all internal circuits and power switch.
6	1	Timing Capacitor	Connect a capacitor to this pin to set the frequency. The addition of a parallel resistor will decrease the maximum duty cycle and increase the frequency.
7	3	V _{CC}	Power pin for the IC.
8	4	I _{pk} Sense	When $(V_{CC}-V_{IPKsense}) > 250$ mV the circuit resets the output driver on a pulse by pulse basis.
9	5	Drive Collector	Voltage driver collector
10,11	6,7,8,9	Switch Collector	Internal switch transistor collector
14,15	10,11,12,13	Switch Emitter	Internal switch transistor emitter
16	14	Bootstrap Input	Connect this pin to V_{CC} for operation at low V_{CC} levels. For some topologies, a series resistor and capacitor can be utilized to improve the converter efficiency.
5,12,13	2	No Connect	These pins have no connection.
Exposed Pad	Exposed Pad	Exposed Pad	The exposed pad beneath the package must be connected to GND (pin 4). Additionally, using proper layout techniques, the exposed pad can greatly enhance the power dissipation capabilities of the NCP3163.

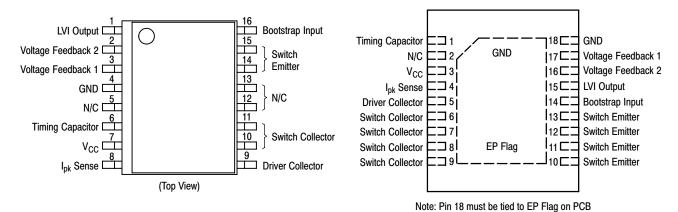
MAXIMUM RATINGS (Note 1)

Rating	Symbol	Value	Unit
Power Supply Voltage	Vcc	0 to +40	V
Switch Collector Voltage Range	V _{CSW}	-1.0 to +40	V
Switch Emitter Voltage Range	V _{ESW}	-2.0 to +40	V
Switch Collector to Emitter Voltage	V _{CESW}	+40	V
Switch Current	I _{SW}	3.4	А
Driver Collector Voltage (Pin 8)	V _{CC}	-1.0 to +40	V
Driver Collector Current (Pin 8)	I _{cc}	150	mA
Bootstrap Input Current Range	I _{BST}	-100 to +100	mA
Current Sense Input Voltage Range	V _{IPKSNS}	$(V_{CC} - 7.0)$ to $(V_{CC} + 1.0)$	V
Feedback and Timing Capacitor Input Voltage Range	V _{in}	-1.0 to +7.0	V
Low Voltage Indicator Output Voltage Range	V _{CLVI}	-1.0 to +40	V
Low Voltage Indicator Output Sink Current	I _{CLVI}	10	mA
Power Dissipation and Thermal Characteristics			
Thermal Characteristics Thermal Resistance, Junction–to–Case Thermal Resistance, Junction–to–Air	$R_{ heta JC} \ R_{ heta JA}$	15 56	°C/W
Storage Temperature Range	T _{stg}	-65 to +150	°C
Maximum Junction Temperature	T _{Jmax}	+150	°C
Operating Ambient Temperature (Note 3) NCP3163PW NCP3163BPW NCV3163PW	T _A	0 to +70 -40 to +85 -40 to +125	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. This device series contains ESD protection and exceeds the following tests: Human Body Model 1500 V per MIL-STD-883, Method 3015. Machine Model Method 150 V.
- This device contains latch-up protection and exceeds 100 mA per JEDEC Standard JESD78.
 Maximum package power dissipation limits must be observed. Maximum Junction Temperature must not be exceeded.
- 4. The pins which are not defined may not be loaded by external signals.

PIN CONNECTIONS



ELECTRICAL CHARACTERISTICS (V_{CC} = 15 V, Pin 16 = V_{CC} , C_T = 270 pF, R_T = 15 k Ω , for typical values T_A = 25°C, for min/max values T_A is the operating ambient temperature range that applies (Note 7), unless otherwise noted.)

	Symbol	Min	Тур	Max	Unit
OSCILLATOR					
Frequency $T_A = 25^{\circ}C$, $V_{CC} = 15 \text{ V}$ Total Variation over $V_{CC} = 2.5 \text{ V}$ to 40 V and Temperature	fosc	225 212	250 250	275 288	kHz
Charge Current	I _{chg}	_	225	_	μΑ
Discharge Current	I _{dischg}	_	25	_	μΑ
Charge to Discharge Current Ratio	I _{chg} /I _{dischg}	8.0	9.0	10.5	_
Sawtooth Peak Voltage	V _{OSC(P)}	-	1.25	-	V
Sawtooth Valley Voltage	V _{OSC(V)}	-	0.55	-	V
FEEDBACK COMPARATOR 1			I		
Threshold Voltage $T_A = 25^{\circ}\text{C}$ Total Variation over $V_{CC} = 2.5 \text{ V}$ to 40 V and Temperature	V _{th(FB1)}	4.9 4.85	5.05 -	5.2 5.25	V
Threshold Voltage Line Regulation (V_{CC} = 2.5 V to 40 V, T_A = 25°C)	REGline _(FB1)	_	0.008	0.03	%/V
Input Bias Current (V _{FB1} = 5.05 V)	I _{IB(FB1)}	_	100	200	μΑ
FEEDBACK COMPARATOR 2	I.	1			
Threshold Voltage $T_A = 25^{\circ}C$, $V_{CC} = 15 \text{ V}$ Total Variation over $V_{CC} = 2.5 \text{ V}$ to 40 V and Temperature	V _{th(FB2)}	1.225 1.213	1.25 -	1.275 1.287	V
Threshold Voltage Line Regulation (V_{CC} = 2.5 V to 40 V, T_A = 25°C)	REGline _(FB1)	_	0.008	0.03	%/V
Input Bias Current (V _{FB2} = 1.25 V)	I _{IB(FB2)}	- 0.4	-	0.4	μΑ
CURRENT LIMIT COMPARATOR					
Threshold Voltage $T_A = 25^{\circ}C$ Total Variation over $V_{CC} = 2.5 \text{ V}$ to 40 V, and Temperature	V _{th(Sense)}	_ 225	250 -	_ 270	mV
Input Bias Current (V _{Ipk (Sense)} = 15 V)	I _{IB} (Sense)	_	1.0	20	μΑ
DRIVER AND OUTPUT SWITCH (Note 6)	, ,				
Saturation Voltage (I_{SW} = 2.5 A, Pins 14, 15 grounded) NCP3163 – Non–Darlington ($R_{Pin~9}$ = 110 Ω to V_{CC} , $I_{SW}/I_{DRV} \approx$ 20) NCV3163 – Non–Darlington ($R_{Pin~9}$ = 110 Ω to V_{CC} , $I_{SW}/I_{DRV} \approx$ 20) Darlington Connection (Pins 9, 10, 11 connected)	V _{CE(sat)}	_ _ _	0.6 0.6 1.0	1.0 1.2 1.4	V
Collector Off–State Leakage Current (V _{CE} = 40 V)	I _{C(off)}	_	0.02	100	μΑ
Bootstrap Input Current Source (V _{BS} = V _{CC} + 5.0 V)	I _{source(DRV)}	0.5	2.0	4.0	mA
Bootstrap Input Zener Clamp Voltage (I _Z = 25 mA)	V _Z	V _{CC} + 6.0	V _{CC} + 7.0	V _{CC} + 9.0	V
LOW VOLTAGE INDICATOR					
Input Threshold (V _{FB2} Increasing)	V_{th}	1.07	1.125	1.18	V
Input Hysteresis (V _{FB2} Decreasing)	V _H	_	15	_	mV
Output Sink Saturation Voltage (I _{sink} = 2.0 mA)	V _{OL(LVI)}	-	0.15	0.4	V
Output Off–State Leakage Current (V _{OH} = 15 V)	I _{OH}	_	0.01	5.0	μΑ
TOTAL DEVICE					
Standby Supply Current (V_{CC} = 2.5 V to 40 V, Pin 8 = V_{CC} , Pins 6, 14, 15 = GND, remaining pins open)	Icc	_	6.0	10	mA

^{5.} Maximum package power dissipation limits must be observed.

Maximum package power dissipation limits the observed.
 Low duty cycle pulse techniques are used during test to maintain junction temperature as close to ambient as possible.
 Tlow = 0°C for NCP3163 Thigh = +70°C for NCP3163 = +85°C for NCP3163B = +85°C for NCP3163B = +125°C for NCV3163

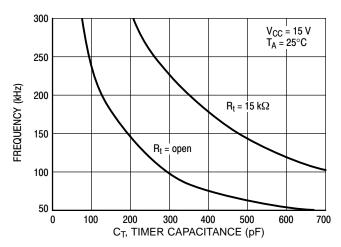


Figure 3. Oscillator Frequency vs. Timer Capacitance (C_T)

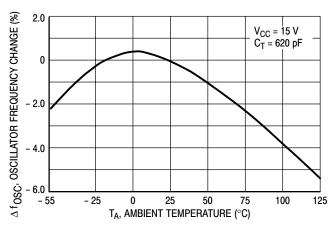


Figure 4. Oscillator Frequency Change vs. Temperature when only C_{T} is connected to Pin 6

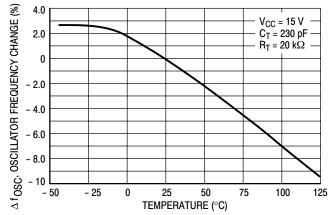


Figure 5. Oscillator Frequency Change vs. Temperature when C_T and R_T are connected to Pin 6

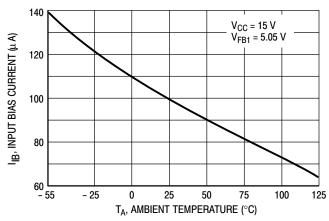


Figure 6. Feedback Comparator 1 Input Bias Current vs. Temperature

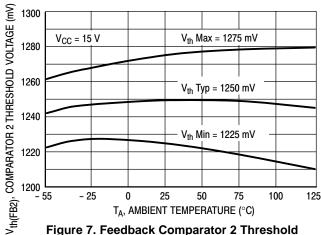


Figure 7. Feedback Comparator 2 Threshold Voltage vs. Temperature

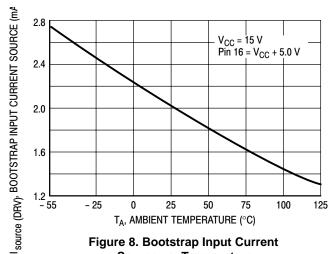


Figure 8. Bootstrap Input Current Source vs. Temperature

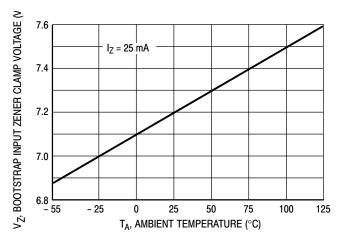


Figure 9. Bootstrap Input Zener Clamp Voltage vs. Temperature

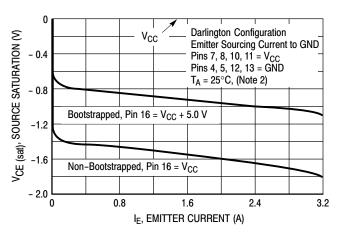


Figure 10. Output Switch Source Saturation vs. Emitter Current

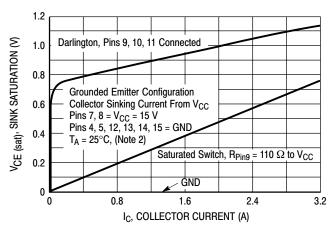


Figure 11. Output Switch Sink Saturation vs. Collector Current

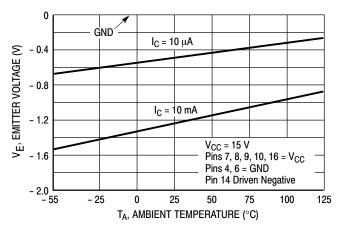


Figure 12. Output Switch Negative Emitter Voltage vs. Temperature

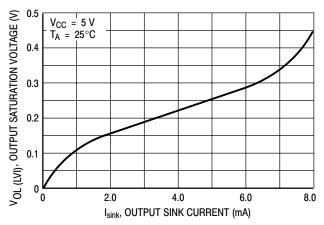


Figure 13. Low Voltage Indicator Output Sink Saturation Voltage vs. Sink Current

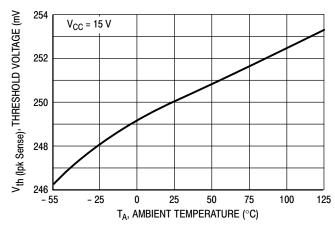


Figure 14. Current Limit Comparator Threshold Voltage vs. Temperature

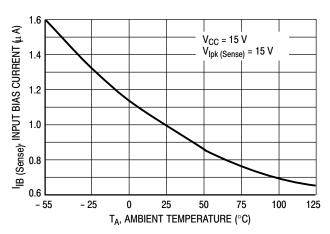


Figure 15. Current Limit Comparator Input Bias
Current vs. Temperature

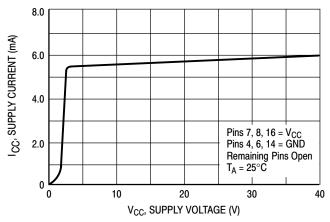


Figure 16. Standby Supply Current vs. Supply Voltage

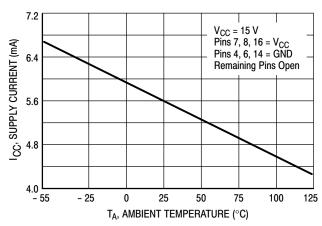


Figure 17. Standby Supply Current vs. Temperature

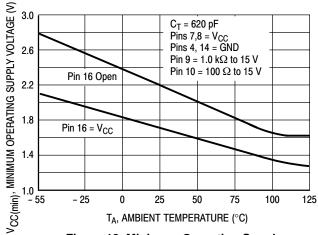


Figure 18. Minimum Operating Supply Voltage vs. Temperature

INTRODUCTION

The NCP3163 is a monolithic power switching regulator optimized for DC-to-DC converter applications. The combination of its features enables the system designer to directly implement step-up, step-down, and voltage-inverting converters with a minimum number of external components. Potential applications include cost sensitive consumer products as well as equipment for the automotive, computer, and industrial markets. A representative block diagram is shown in Figure 2.

OPERATING DESCRIPTION

The NCP3163 operates as a fixed on-time, variable off-time voltage mode ripple regulator. In general, this mode of operation is somewhat analogous to a capacitor charge pump and does not require dominant pole loop compensation for converter stability. The Typical Operating Waveforms are shown in Figure 19. The output voltage waveform shown is for a step-down converter with the ripple and phasing exaggerated for clarity. During initial converter startup, the feedback comparator senses that the output voltage level is below nominal. This causes the output switch to turn on and off at a frequency and duty cycle controlled by the oscillator, thus pumping up the output filter capacitor. When the output voltage level reaches nominal, the feedback comparator sets the latch, immediately terminating switch conduction. The feedback comparator will inhibit the switch until the load current causes the output voltage to fall below nominal. Under these conditions, output switch conduction can be inhibited for a partial

oscillator cycle, a partial cycle plus a complete cycle, multiple cycles, or a partial cycle plus multiple cycles.

Oscillator

The oscillator frequency and on–time of the output switch are programmed by the value selected for timing capacitor C_T. Capacitor C_T is charged and discharged by a 9 to 1 ratio internal current source and sink, generating a negative going sawtooth waveform at Pin 6. As C_T charges, an internal pulse is generated at the oscillator output. This pulse is connected to the NOR gate center input, preventing output switch conduction, and to the AND gate upper input, allowing the latch to be reset if the comparator output is low. Thus, the output switch is always disabled during ramp-up and can be enabled by the comparator output only at the start of ramp-down. The oscillator peak and valley thresholds are 1.25 V and 0.55 V, respectively, with a charge current of 225 µA and a discharge current of 25 µA, yielding a maximum on-time duty cycle of 90%. A reduction of the maximum duty cycle may be required for specific converter configurations. This can be accomplished with the addition of an external deadtime resistor (RDT) placed across CT. The resistor increases the discharge current which reduces the on-time of the output switch. The converter output can be inhibited by clamping C_T to ground with an external NPN small-signal transistor. To calculate the frequency when only C_T is connected to Pin 6, use the equations found in Figure 22. When R_T is also used, the frequency and maximum duty cycle can be calculated with the NCP3163 design tool found at www.onsemi.com.

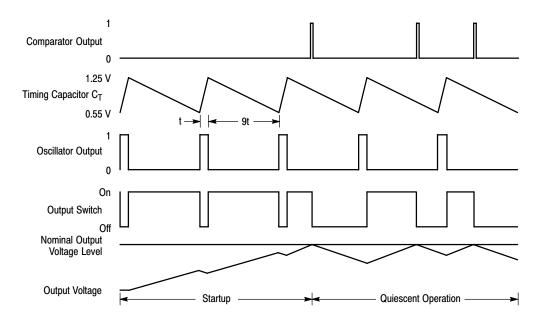


Figure 19. Typical Operating Waveforms

Feedback and Low Voltage Indicator Comparators

Output voltage control is established by the Feedback comparator. The inverting input is internally biased at 1.25 V and is not pinned out. The converter output voltage is typically divided down with two external resistors and monitored by the high impedance noninverting input at Pin 2. The maximum input bias current is $\pm 0.4 \,\mu\text{A}$, which can cause an output voltage error that is equal to the product of the input bias current and the upper divider resistance value. For applications that require 5.0 V, the converter output can be directly connected to the noninverting input at Pin 3. The high impedance input, Pin 2, must be grounded to prevent noise pickup. The internal resistor divider is set for a nominal voltage of 5.05 V. The additional 50 mV compensates for a 1.0% voltage drop in the cable and connector from the converter output to the load. The Feedback comparator's

output state is controlled by the highest voltage applied to either of the two noninverting inputs.

The Low Voltage Indicator (LVI) comparator is designed for use as a reset controller in microprocessor—based systems. The inverting input is internally biased at 1.125 V, which sets the noninverting input thresholds to 90% of nominal. The LVI comparator has 15 mV of hysteresis to prevent erratic reset operation. The Open Collector output is capable of sinking in excess of 6.0 mA (see Figure 13). An external resistor (R_{LVI}) and capacitor (C_{DLY}) can be used to program a reset delay time (t_{DLY}) by the formula shown below, where $V_{th(MPU)}$ is the microprocessor reset input threshold. Refer to Figure 20.

$$t_{DLY} = R_{LVI} \cdot C_{DLY} \cdot In \left(\frac{1}{1 - \frac{V_{th(MPU)}}{V_{out}}} \right)$$

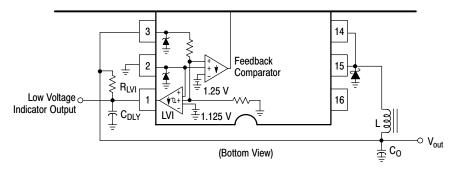


Figure 20. Partial Application Schematic Showing Implementation of LVI Delay with R_{LVI} and C_{DLY}

Current Limit Comparator, Latch and Thermal Shutdown

With a voltage mode ripple converter operating under normal conditions, output switch conduction is initiated by the oscillator and terminated by the Voltage Feedback comparator. Abnormal operating conditions occur when the converter output is overloaded or when feedback voltage sensing is lost. Under these conditions, the Current Limit comparator will protect the Output Switch.

The switch current is converted to a voltage by inserting a fractional ohm resistor, R_{SC} , in series with V_{CC} and output switch transistor Q_2 . The voltage drop across R_{SC} is monitored by the Current Sense comparator. If the voltage drop exceeds 250 mV with respect to V_{CC} , the comparator will set the latch and terminate output switch conduction on a cycle–by–cycle basis. This Comparator/Latch configuration ensures that the Output Switch has only a single on–time during a given oscillator cycle. The calculation for a value of R_{SC} is:

$$R_{SC} = \frac{0.25 \text{ V}}{I_{pk} \text{ (Switch)}}$$

Figures 14 and 15 show that the Current Sense comparator threshold is tightly controlled over temperature and has a typical input bias current of 1.0 μ A. The propagation delay from the comparator input to the Output Switch is typically

200 ns. The parasitic inductance associated with R_{SC} and the circuit layout should be minimized. This will prevent unwanted voltage spikes that may falsely trip the Current Limit comparator.

Internal thermal shutdown circuitry is provided to protect the IC in the event that the maximum junction temperature is exceeded. When activated, typically at 170°C, the Latch is forced into the "Set" state, disabling the Output Switch. This feature is provided to prevent catastrophic failures from accidental device overheating. It is not intended to be used as a replacement for proper heatsinking.

Driver and Output Switch

To aid in system design flexibility and conversion efficiency, the driver current source and collector, and output switch collector and emitter are pinned out separately. This allows the designer the option of driving the output switch into saturation with a selected force gain or driving it near saturation when connected as a Darlington. The output switch has a typical current gain of 70 at 2.5 A and is designed to switch a maximum of 40 V collector to emitter, with up to 3.4 A peak collector current. The minimum value for R_{SC} is:

$$RSC(min) = \frac{0.25 \text{ V}}{3.4 \text{ A}} = 0.0735 \Omega$$

When configured for step-down or voltage-inverting applications (see application notes at the end of this document) the inductor will forward bias the output rectifier when the switch turns off. Rectifiers with a high forward voltage drop or long turn-on delay time should not be used. If the emitter is allowed to go sufficiently negative, collector current will flow, causing additional device heating and reduced conversion efficiency.

Figure 12 shows that by clamping the emitter to 0.5 V, the collector current will be in the range 10 μA over temperature. A 1N5822 or equivalent Schottky barrier rectifier is recommended to fulfill these requirements.

A bootstrap input is provided to reduce the output switch saturation voltage in step-down and voltage-inverting converter applications. This input is connected through a series resistor and capacitor to the switch emitter and is used to raise the internal 2.0 mA bias current source above $V_{\rm CC}$. An internal zener limits the bootstrap input voltage to $V_{\rm CC}$ +7.0 V. The capacitor's equivalent series resistance must limit the zener current to less than 100 mA. An additional series resistor may be required when using tantalum or other

low ESR capacitors. The equation below is used to calculate a minimum value bootstrap capacitor based on a minimum zener voltage and an upper limit current source.

$$C_{B(min)} = I \frac{\Delta t}{\Delta V} = 4.0 \text{ mA} \frac{t_{ON}}{4.0 \text{ V}} = 0.001 t_{ON}$$

Parametric operation of the NCP3163 is guaranteed over a supply voltage range of 2.5 V to 40 V. When operating below 3.0 V, the Bootstrap Input should be connected to V_{CC} . Figure 18 shows that functional operation down to 1.7 V at room temperature is possible.

Package

The NCP3163 is contained in a heatsinkable 16-lead plastic package in which the die is mounted on a special heat tab copper alloy pad. This pad is designed to be soldered directly to a GND connection on the printed circuit board to improve thermal conduction. Since this pad directly contacts the substrate of the die, it is important that this pad be always soldered to GND, even if surface mount heat sinking is not being used. Figure 21 shows recommended layout techniques for this package.

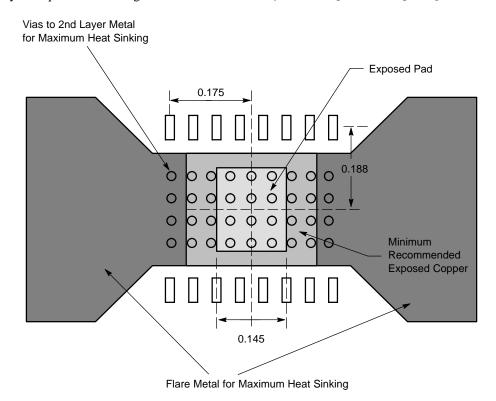


Figure 21. Layout Guidelines to Obtain Maximum Package Power Dissipation

APPLICATIONS

Figures 23 through 30 show the simplicity and flexibility of the NCP3163. Three main converter topologies are demonstrated with actual test data shown below each of the circuit diagrams. Figure 22 gives the relevant design

equations for the key parameters. Additionally, a complete application design aid for the NCP3163 can be found at www.onsemi.com.

Calculation	Step-Down	Step-Up	Voltage-Inverting
(See Notes 1,2,3) ton toff	$\frac{V_{out} + V_{F}}{V_{in} - V_{sat} - V_{out}}$	$\frac{V_{out} + V_{F} - V_{in}}{V_{in} - V_{sat}}$	$\frac{ V_{out} + V_{F}}{V_{in} - V_{sat}}$
ton	$f\left(\frac{\frac{t_{on}}{t_{off}}}{\left(\frac{t_{on}}{t_{off}} + 1\right)}\right)$	$f\left(\frac{\frac{t_{\text{On}}}{t_{\text{off}}}}{\left(\frac{t_{\text{On}}}{t_{\text{off}}} + 1\right)}\right)$	$f\left(\frac{\frac{t_{\text{on}}}{t_{\text{off}}}}{\left(\frac{t_{\text{on}}}{t_{\text{off}}} + 1\right)}\right)$
СТ	$\frac{32.143 \cdot 10^{-6}}{f} - 20 \cdot 10^{-12}$	$\frac{32.143 \cdot 10^{-6}}{f} - 20 \cdot 10^{-12}$	$\frac{32.143 \cdot 10^{-6}}{f} - 20 \cdot 10^{-12}$
I _L (avg)	lout	$I_{out}\left(\frac{t_{on}}{t_{off}} + 1\right)$	$I_{out}\left(\frac{t_{on}}{t_{off}} + 1\right)$
lpk (Switch)	$I_{L(avg)} + \frac{\Delta I_{L}}{2}$	$I_{L(avg)} + \frac{\Delta I_{L}}{2}$	$I_{L(avg)} + \frac{\Delta I_{L}}{2}$
R _{SC}	0.25 Ipk (Switch)	0.25 ^I pk (Switch)	0.25 ^I pk (Switch)
L	$\left(\frac{V_{in} - V_{sat} - V_{out}}{\Delta I_{L}}\right) t_{on}$	$\left(\frac{V_{in} - V_{sat}}{\Delta I_{L}}\right) t_{on}$	$\left(\frac{V_{in} - V_{sat}}{\Delta I_{L}}\right) t_{on}$
V _{ripple(pp)}	$\Delta I_L \sqrt{\left(\frac{1}{8 f C_O}\right)^2 + (ESR)^2}$	$\approx \frac{t_{on} l_{out}}{c_{o}}$	$\approx \frac{t_{on} I_{out}}{C_{O}}$
V _{out}	$V_{ref}\left(\frac{R_2}{R_1} + 1\right)$	$V_{ref}\left(\frac{R_2}{R_1} + 1\right)$	$V_{ref}\left(\frac{R_2}{R_1} + 1\right)$

The following Converter Characteristics must be chosen:

V_{in} - Nominal operating input voltage.

V_{out} – Desired output voltage.

I_{out} – Desired output current.

- ΔI_L Desired peak–to–peak inductor ripple current. For maximum output current it is suggested that ΔI_L be chosen to be less than 10% of the average inductor current $I_{L(avg)}$. This will help prevent I_{pk} (Switch) from reaching the current limit threshold set by R_{SC}. If the design goal is to use a minimum inductance value, let $\Delta I_L = 2(I_{L(avg)})$. This will proportionally reduce converter output current capability.
 - *f* Maximum output switch frequency.

V_{ripple(pp)} – Desired peak–to–peak output ripple voltage. For best performance the ripple voltage should be kept to a low value since it will directly affect line and load regulation. Capacitor C_O should be a low equivalent series resistance (ESR) electrolytic designed for switching regulator applications.

NOTES: 1. V_{sat} – Saturation voltage of the output switch, refer to Figures 10 and 11.

- 2. V_F Output rectifier forward voltage drop. Typical value for 1N5822 Schottky barrier rectifier is 0.5 V.
- 3. The calculated t_{on}/t_{off} must not exceed the minimum guaranteed oscillator charge to discharge ratio of 8, at the minimum operating input voltage.

Figure 22. Design Equations

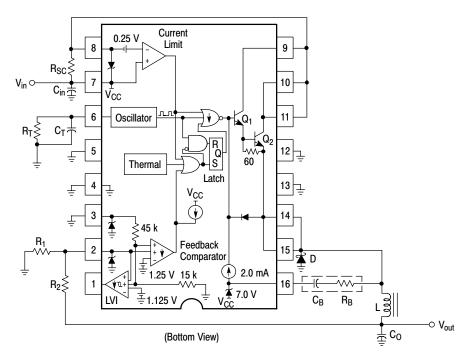


Figure 23. Typical Buck Application Schematic

Value of Components

Name Value		
L	47 μΗ	
D	2 A, 40 V Schottky Rectifier	
C _{in}	47 μF, 35 V	
C _{out}	100 μF, 10 V	
Ct	270 pF ±10%	
R _t	15 kΩ	

Name	Value
R ₁	15 kΩ
R ₂	24.9 kΩ
R _{sc}	80 mΩ, 1 W
C _b	4.7 nF
R _b	200 Ω

Test Results for V_{out} = 3.3 V

Test	Condition	Results
Line Regulation	V _{in} = 8.0 V to 24 V, I _{out} = 2.5 A	13 mV
Load Regulation	V _{in} = 12 V, I _{out} = 0 to 2.5 A	25 mV
Output Ripple	V _{in} = 12 V, I _{out} = 0 to 2.5 A	100 mVpp
Efficiency	V _{in} = 12 V, I _{out} = 2.5 A	70.3%
Short Circuit Current	V_{in} = 12 V, R_L = 0.1 Ω	3.1 A

Test Results for $V_{out} = 5.05 \text{ V}$

Test	Condition	Results
Line Regulation	V _{in} = 10.2 V to 24 V, I _{out} = 2.5 A	54 mV
Load Regulation	V _{in} = 12 V, I _{out} = 0 to 2.5 A	28 mV
Output Ripple	V _{in} = 12 V, I _{out} = 0 to 2.5 A	150 mVpp
Efficiency	V _{in} = 12 V, I _{out} = 2.5 A	75.5%
Short Circuit Current	V_{in} = 12 V, R_L = 0.1 Ω	3.1 A

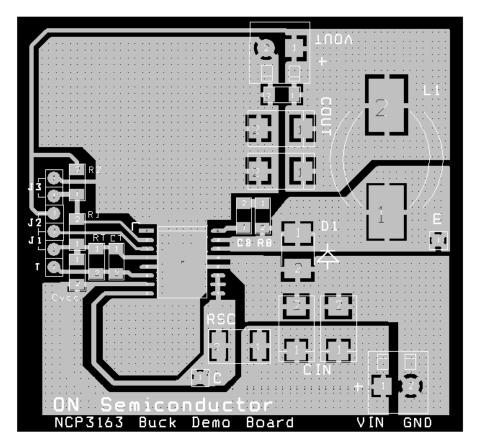


Figure 24. Buck Layout

APPLICATION SPECIFIC CHARACTERISTICS

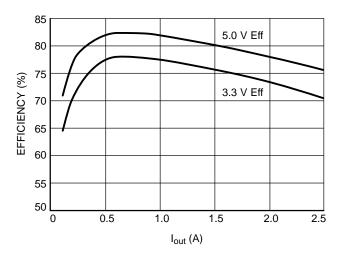


Figure 25. Efficiency vs. Output Current for the Buck Demo Board at V_{in} = 12 V, T_A = 25°C

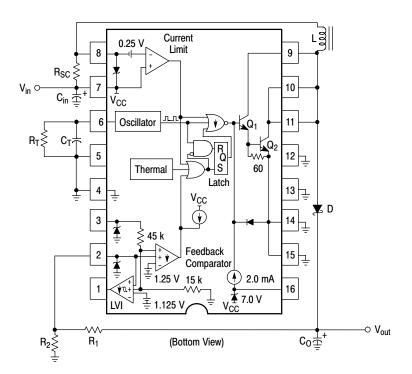


Figure 26. Typical Boost Application Schematic

Value of Components for $V_{out} = 24 \text{ V}$

Name	Value			
L	33 μΗ			
D	2 A, 40 V Schottky Rectifier			
C _{in}	330 μF, 35 V			
C _t	270 pF ±10%			
R _t	15 kΩ			

Name	Value
R ₁	42.2 kΩ
R ₂	2.32 kΩ
C _{out}	330 μF, 25 V
R _{sc}	80 mΩ, 1 W

Test Results for $V_{out} = 24 \text{ V}$

Test	Condition	Results
Line Regulation	V _{in} = 10 V to 20 V, I _{out} = 700 mA	90 mV
Load Regulation	V _{in} = 12 V, I _{out} = 0 to 700 mA	80 mV
Output Ripple	V _{in} = 12 V, I _{out} = 0 to 700 mA	300 mVpp
Efficiency	V _{in} = 12 V, I _{out} = 700 mA	83%
Short Circuit Current	V_{in} = 12 V, R_L = 0.1 Ω	3.1 A

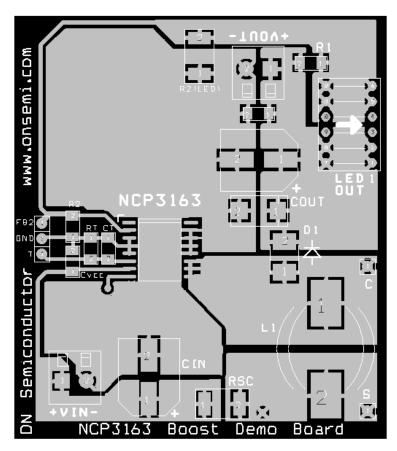


Figure 27. Boost Demo Board Layout

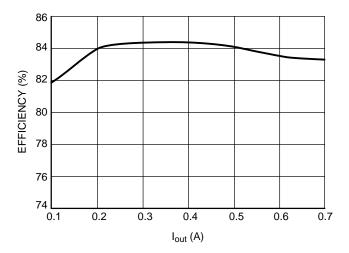


Figure 28. Efficiency vs. Output Current for the Boost Demo Board at V_{in} = 12 V, T_A = 25°C

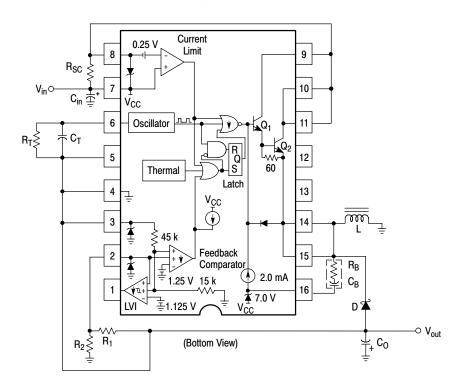


Figure 29. Typical Voltage Inverting Application Schematic

Value of Components for $V_{out} = -15 \text{ V}$

Name	Value		
L	47 μΗ		
D	2 A, 40 V Schottky Rectifier		
C _{in}	270 μF, 16 V		
C _{out}	2 X 270 μF, 16 V		
Ct	150 pF ±10%		

Name	Value	
R ₁	1.07 kΩ	
R ₂	11.8 kΩ	
R _{sc}	80 mΩ, 1 W	
C _b	4.7 nF	
R _b	200 mΩ	

Test Results for $V_{out} = -15 \text{ V}$

Test	Condition	Results
Line Regulation	V _{in} = 7.0 V to 16 V, I _{out} = 500 mA	35 mV
Load Regulation	V _{in} = 12 V, I _{out} = 0 to 500 mA	20 mV
Output Ripple	V _{in} = 12 V, I _{out} = 0 to 500 mA	100 mVpp
Efficiency	V _{in} = 12 V, I _{out} = 500 mA	68%
Short Circuit Current	V_{in} = 12 V, R_L = 0.1 Ω	3.1 A

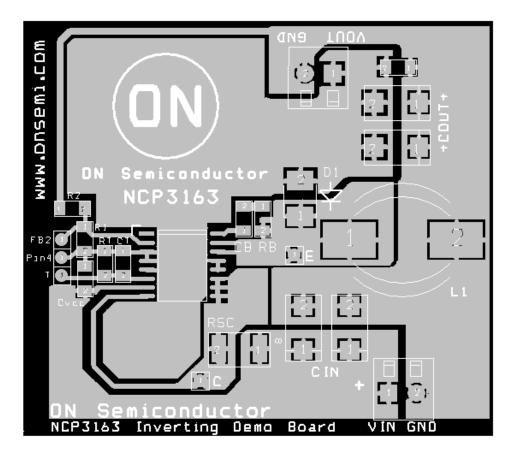


Figure 30. Voltage Inverting Demo Board Layout

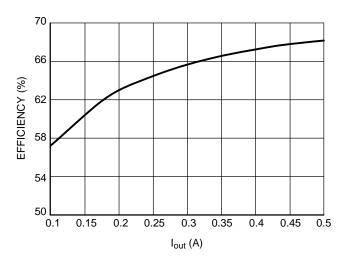


Figure 31. Efficiency vs. Output Current for the Voltage Inverting Demo Board at V_{in} = 12 V, T_A = 25°C

ORDERING INFORMATION

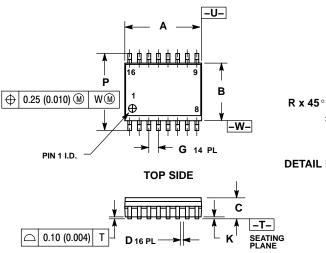
Device	Package	Shipping [†]
NCP3163PWG	SOIC-16 W Exposed Pad (Pb-Free)	47 Units / Rail
NCP3163PWR2G	SOIC-16 W Exposed Pad (Pb-Free)	1000 / Tape & Reel
NCP3163BPWG	SOIC-16 W Exposed Pad (Pb-Free)	47 Units / Rail
NCP3163BPWR2G	SOIC-16 W Exposed Pad (Pb-Free)	1000 / Tape & Reel
NCP3163MNR2G	DFN18 (Pb-Free)	2500 / Tape & Reel
NCP3163BMNR2G	DFN18 (Pb-Free)	2500 / Tape & Reel
NCV3163PWG	SOIC-16 W Exposed Pad (Pb-Free)	47 Units / Rail
NCV3163PWR2G	SOIC-16 W Exposed Pad (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOIC 16 LEAD WIDE BODY, EXPOSED PAD **PW SUFFIX**

CASE 751AG-01 ISSUE O



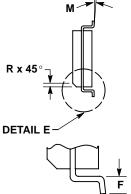
0.25 (0.010) M

BACK SIDE

EXPOSED PAD

Т

USWS



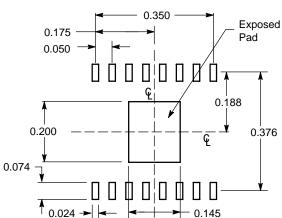
DETAIL E

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- SIDE.

 5 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE PROTRUSION SHALL BE
 0.13 (0.005) TOTAL IN EXCESS OF THE D DIMENSION
 AT MAXIMUM MATERIAL CONDITION.
- 6. 751R-01 OBSOLETE, NEW STANDARD 751R-02.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	10.15	10.45	0.400	0.411
В	7.40	7.60	0.292	0.299
С	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
Н	3.31	3.51	0.130	0.138
J	0.25	0.32	0.010	0.012
K	0.00	0.10	0.000	0.004
L	4.58	4.78	0.180	0.188
M	0 °	7 °	0 °	7 °
Р	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

SOLDERING FOOTPRINT*

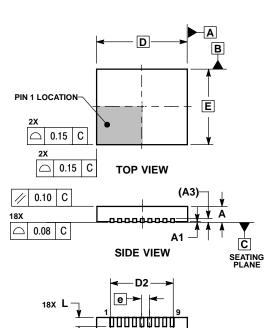


DIMENSIONS: INCHES

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

DFN18 CASE 505-01 ISSUE D



E2

18X **b**

Ф

0.10

0.05

CAB

C NOTE 3

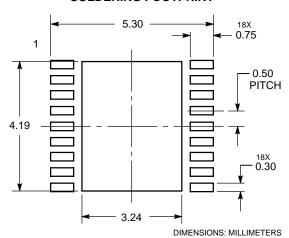
10

BOTTOM VIEW

- NOTES:
 1. DIMENSIONS AND TOLERANCING PER
 - ASME Y14.5M, 1994.
 DIMENSIONS IN MILLIMETERS.
- DIMENSIONS IN MILLIME TERS.
 DIMENSION 5 APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
 0.25 AND 0.30 MM FROM TERMINAL
 COPLANARITY APPLIES TO THE EXPOSED
 PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
A3	0.20 REF		
b	0.18	0.30	
D	6.00 BSC		
D2	3.98	4.28	
Е	5.00 BSC		
E2	2.98	3.28	
е	0.50 BSC		
K	0.20		
L	0.45	0.65	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

18X K

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative